



Material Content Data Sheet



Sales Product Name		BSC0901NS		Issued		22. January 2018		
MA#		MA001275374						
Package		PG-TDSON-8-6		Weight*		118.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.671	0.57	0.57	5663	5663
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		319	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.87	31.91	318694	319109
wire	noble metal	gold	7440-57-5	0.052	0.04	0.04	438	438
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		738	
	plastics	epoxy resin	-	6.209	5.24		52404	
	inorganic material	silicondioxide	60676-86-0	37.430	31.59	36.90	315899	369041
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12251	12251
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1397	1397
solder	noble metal	silver	7440-22-4	0.024	0.02		202	
	non noble metal	tin	7440-31-5	0.019	0.02		161	
	non noble metal	lead	7439-92-1	0.912	0.77	0.81	7698	8061
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.55	9.56	95537	95662
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	copper	7440-50-8	22.292	18.81	18.84	188133	188378
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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